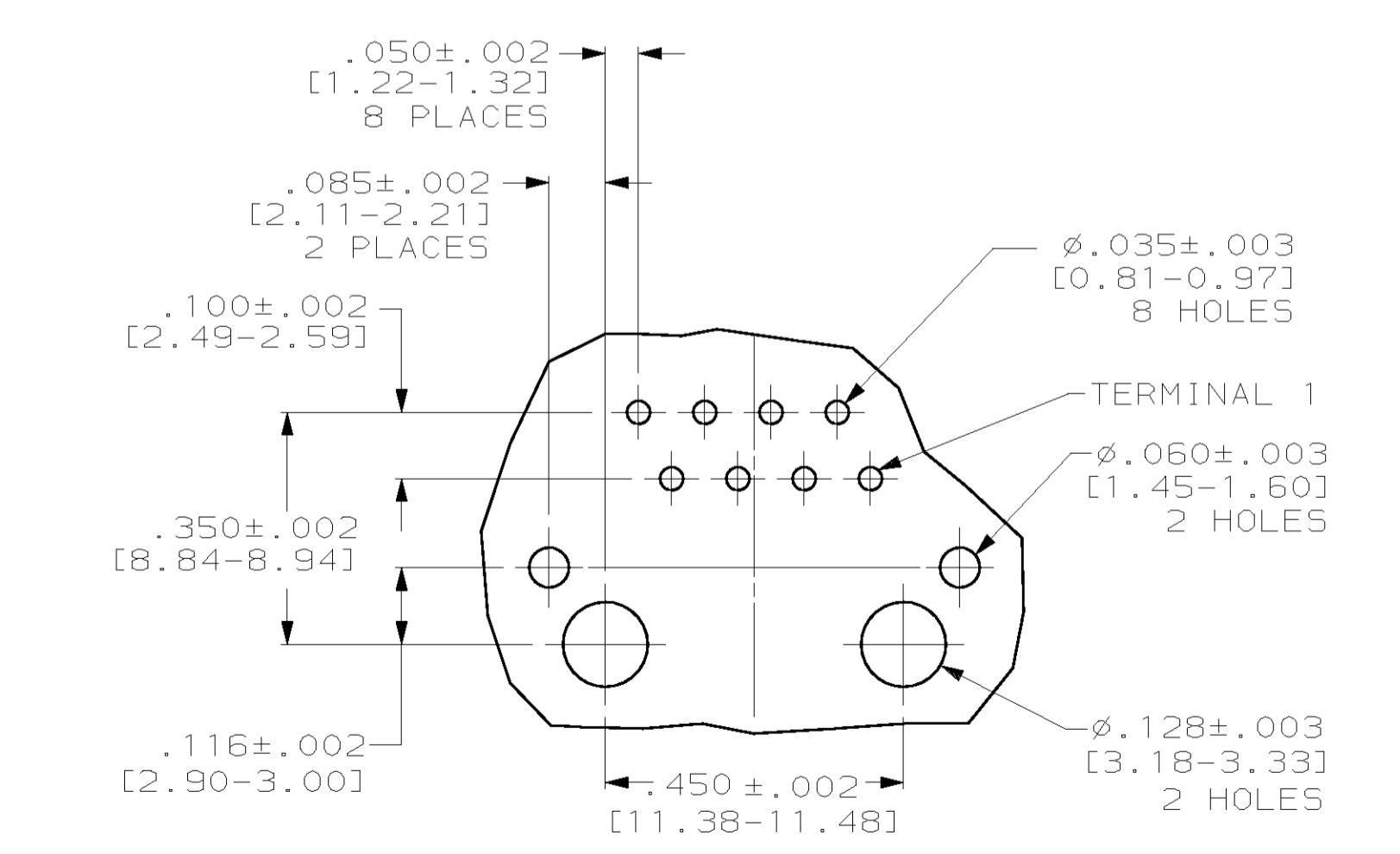
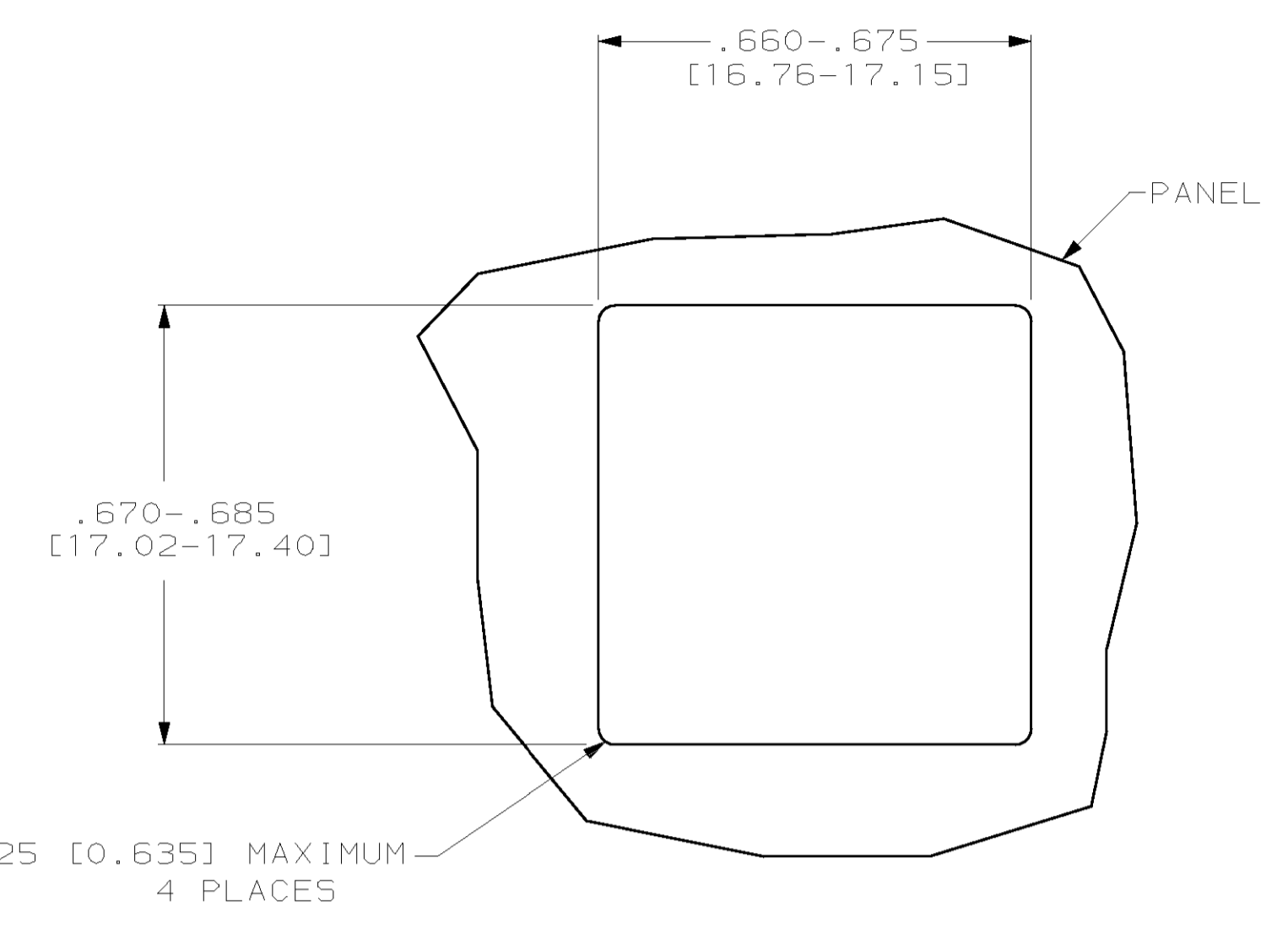
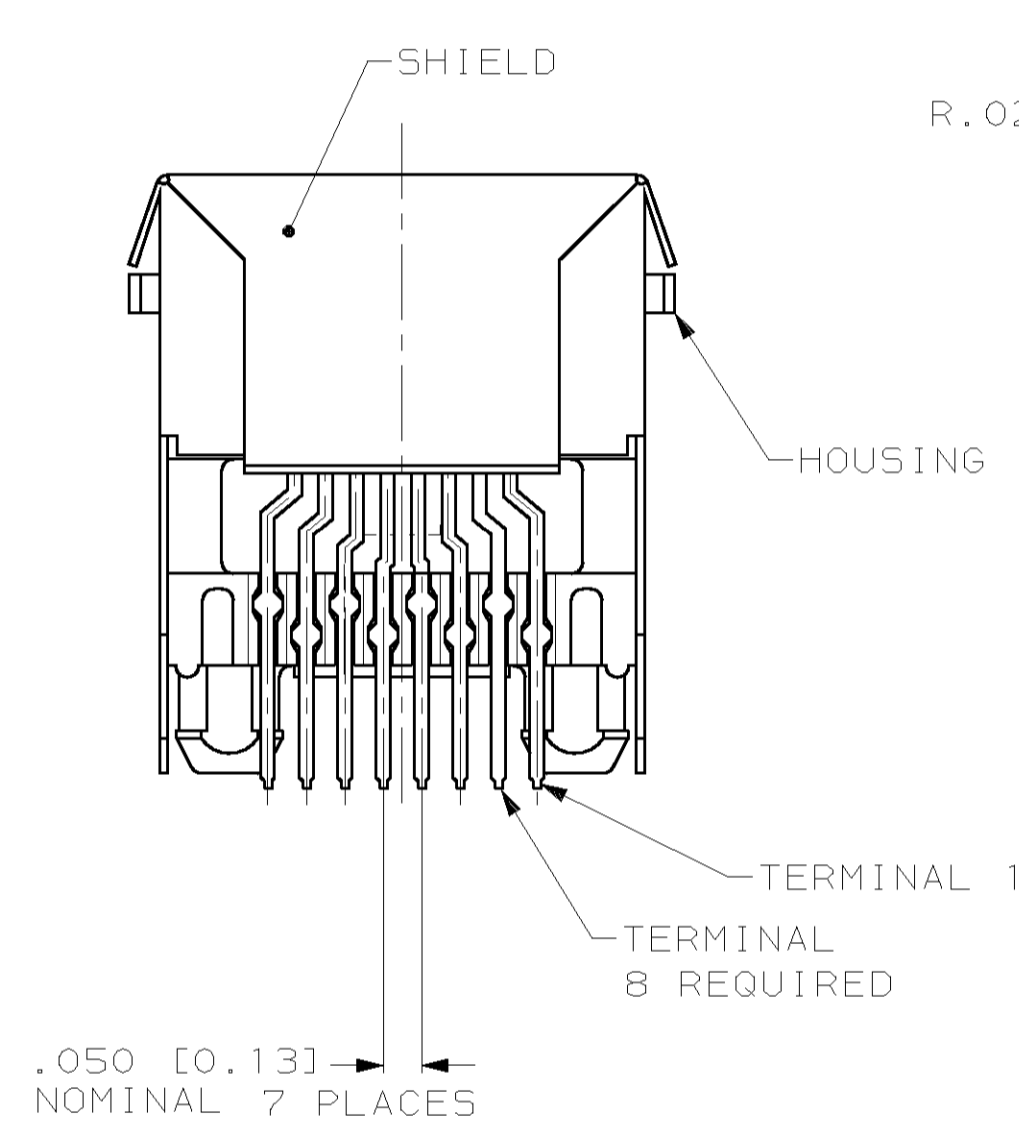
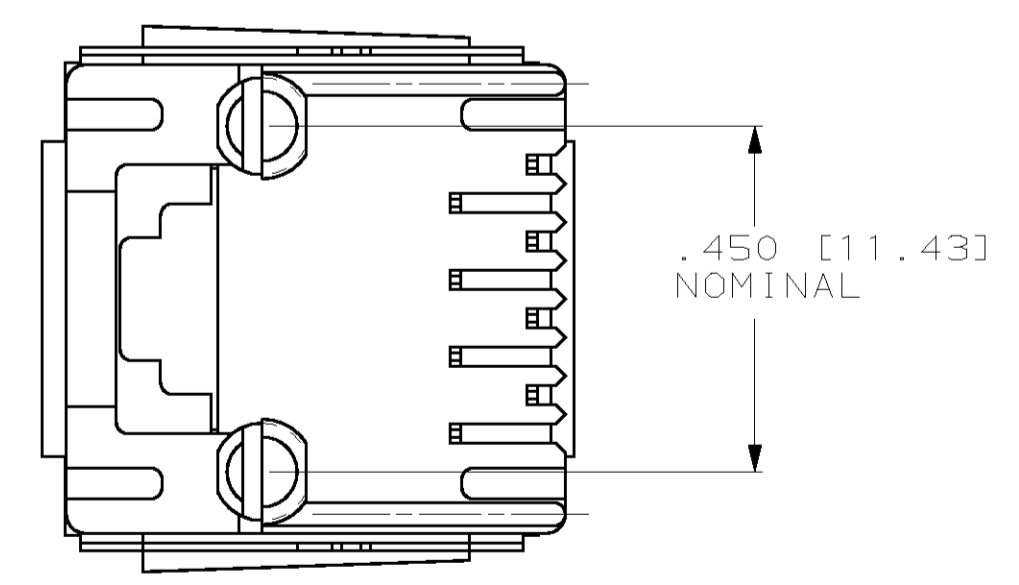
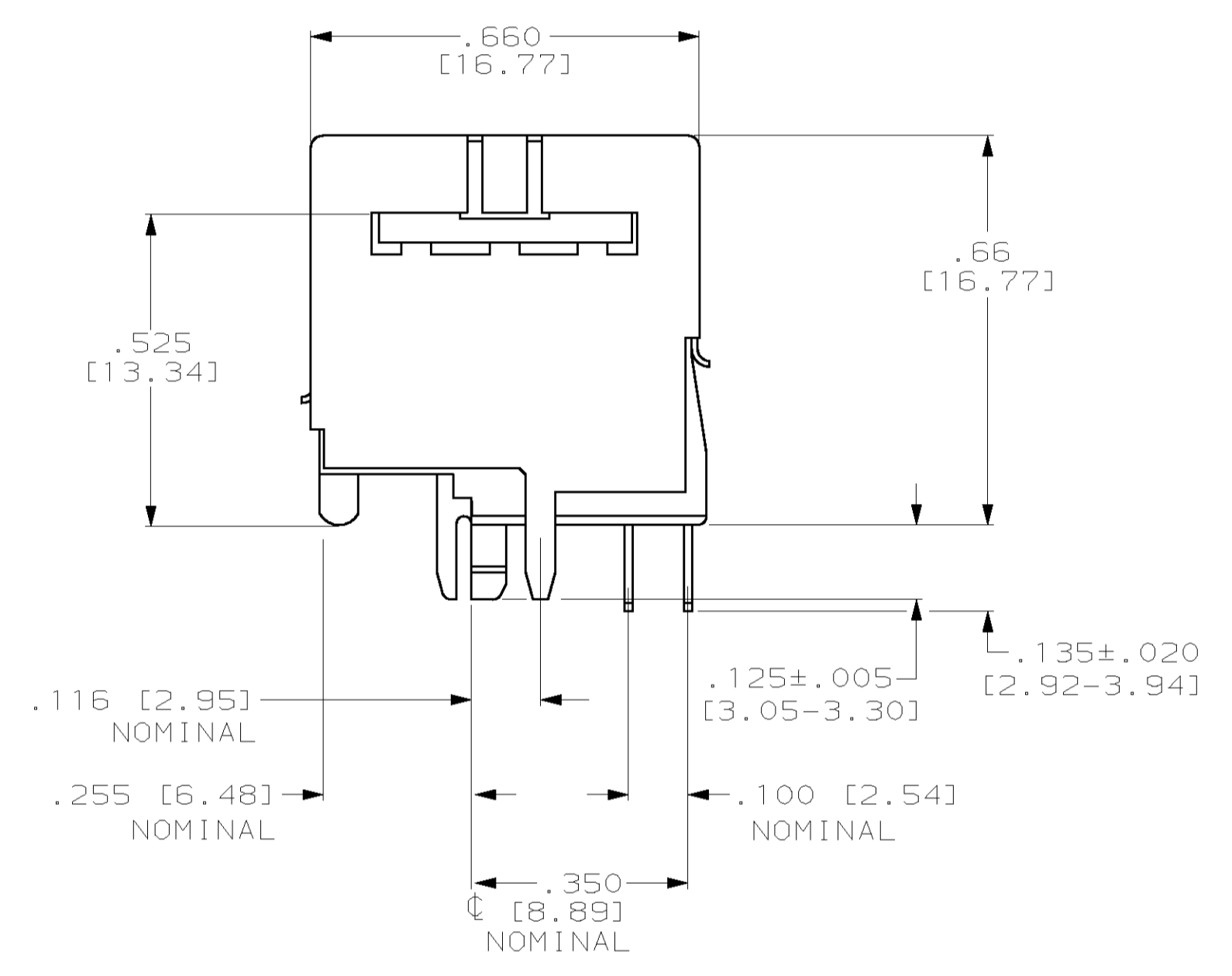
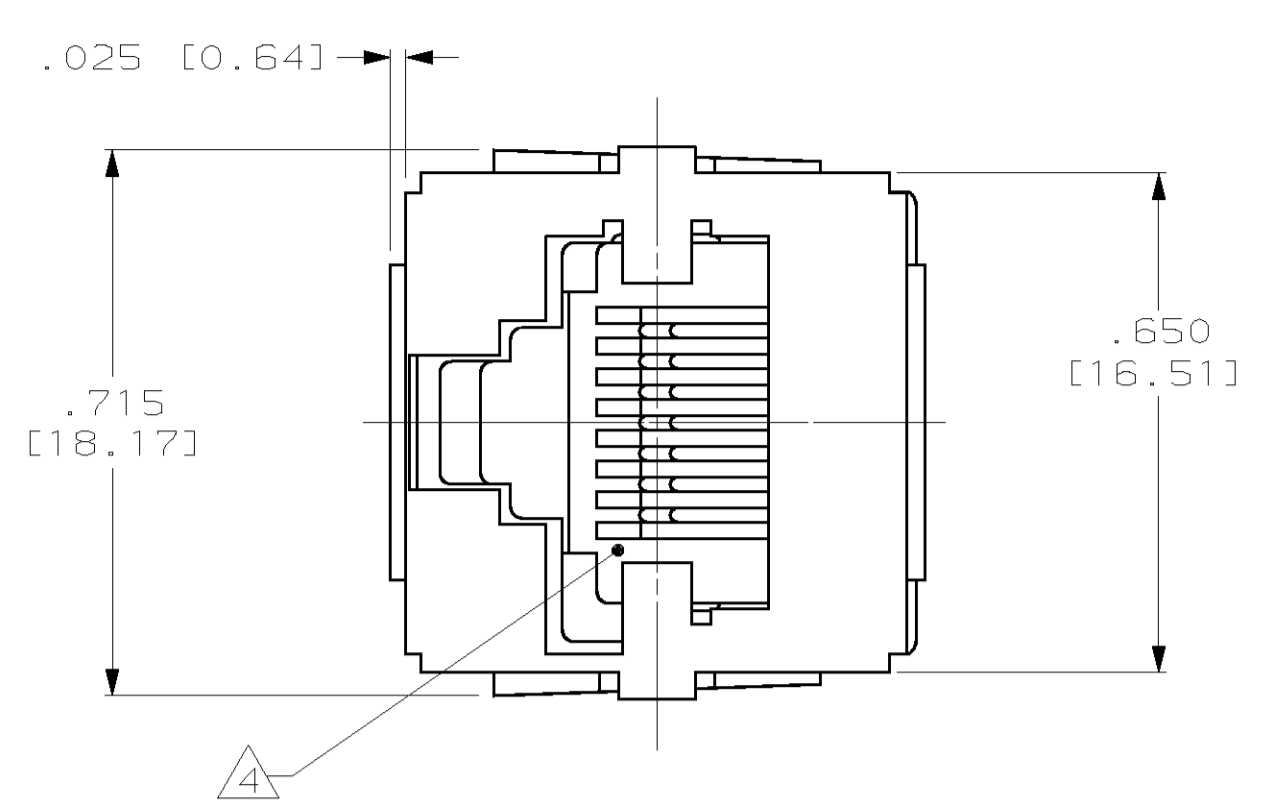


LOC	DIST	REV	DATE	BY	APPV
AA	22	B	22MAY00	DLD	CMB



- ⚠ DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 2. DIMENSIONS IN BRACKETS [ ] ARE IN MILLIMETERS.
- ⚠ MATERIAL: HOUSING - POLYESTER MOLDING COMPOUND, BLACK.  
 TERMINALS - .0138 [0.350] THICK PH05 BRONZE PLATED WITH .000050 [1.27μm] MINIMUM THICK GOLD IN LOCALIZED AREA AND .000150 [3.81μm] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER .000050 [1.27μm] MINIMUM THICK NICKLE UNDERPLATE.  
 SHIELD - COPPER ZINC ALLOY PLATED WITH .000080 [2.03μm] MINIMUM THICK TIN-LEAD OVER .000100 [2.54μm] MINIMUM THICK COPPER UNDERPLATE.
- ⚠ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 5. FOR PERFORMANCE REQUIREMENTS SEE AMP SPECIFICATION 108-1163.

557730-1  
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN D. STRAUSSER 8/17/92	AMP Incorporated Harrisburg, PA 17105-3608
DIMENSIONS (INCHES [mm])		CHK B. FOX 9/30/92	NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPV J. TONEY 10/06/92	PRODUCT SPEC
0 PLC	±	APPLICATION SPEC	SIZE 114-2048
1 PLC	±	WEIGHT	A1 00779
2 PLC	±	CUSTOMER DRAWING	SCALE 4:1
3 PLC	±		SHEET 1 OF 1
4 PLC	±		REV B
ANGLES	±		
FINISH	±		